



FDB8443

N-Channel PowerTrench® MOSFET

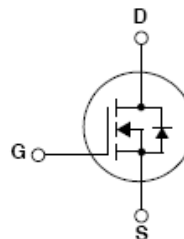
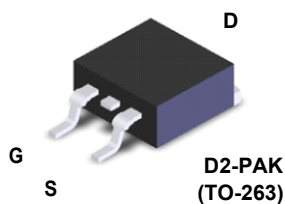
40 V, 182 A, 3.0 mΩ

Features

- $R_{DS(on)} = 2.3\text{ m}\Omega$ (Typ.)@ $V_{GS} = 10\text{ V}$, $I_D = 80\text{ A}$
- $Q_{G(tot)} = 142\text{ nC}$ (Typ.)
- Low Miller Charge, $Q_{GD} = 32\text{ nC}$ (Typ.)
- UIS Capability (Single Pulse and Repetitive Pulse)
- RoHS Compliant

Applications

- Power Tools
- Motor drives and Uninterruptible Power Supplies
- Synchronous Rectification
- Battery Protection Circuit



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FDB8443	Unit
V_{DSS}	Drain to Source Voltage	40	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current	- Continuous ($T_C = 25^\circ\text{C}$, Silicon Limited)	182*
		- Continuous ($T_C = 100^\circ\text{C}$, Silicon Limited)	129*
		- Continuous ($T_C = 25^\circ\text{C}$, Package Limited)	120
		- Continuous ($T_A = 25^\circ\text{C}$, $R_{\theta JA} = 43^\circ\text{C/W}$)	25
I_{DM}	Drain Current	- Pulsed	See Figure 4
E_{AS}	Single Pulse Avalanche Energy (Note 1)	531	mJ
P_D	Power Dissipation	188	W
	Derate above 25°C	1.25	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature	-55 to +175	$^\circ\text{C}$

*Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 120A.

Thermal Characteristics

Symbol	Parameter	FDB8443	Unit
$R_{\theta JC}$	Thermal Resistance Junction to Case, Max.	0.8	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient, Max. (Note 2)	62	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-263, 1 in^2 copper pad area, Max.	43	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB8443	FDB8443	TO-263AB	330mm	24mm	800 units

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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Off Characteristics

B_{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 32\text{V},$ $V_{GS} = 0\text{V}$	-	-	1	μA
		$T_C = 150^\circ\text{C}$	-	-	250	
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	2	2.8	4	V
$r_{DS(on)}$	Drain to Source On Resistance	$I_D = 80\text{A}, V_{GS} = 10\text{V}$	-	2.3	3.0	$\text{m}\Omega$
		$I_D = 80\text{A}, V_{GS} = 10\text{V},$ $T_J = 175^\circ\text{C}$	-	4.2	5.5	

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$	-	9310	-	pF
C_{oss}	Output Capacitance		-	800	-	pF
C_{rss}	Reverse Transfer Capacitance		-	510	-	pF
R_G	Gate Resistance	$V_{GS} = 0.5\text{V}, f = 1\text{MHz}$	-	0.9	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V	-	142	185	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0$ to 2V	-	17.5	23	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DD} = 20\text{V}$ $I_D = 35\text{A}$ $I_g = 1\text{mA}$	-	36	-	nC
Q_{gs2}	Gate Charge Threshold to Plateau		-	18.8	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		-	32	-	nC

Switching Characteristics ($V_{GS} = 10\text{V}$)

t_{on}	Turn-On Time	$V_{DD} = 20\text{V}, I_D = 35\text{A}$ $V_{GS} = 10\text{V}, R_{GS} = 2\Omega$	-	-	58	ns
$t_{d(on)}$	Turn-On Delay Time		-	18.4	-	ns
t_r	Rise Time		-	17.9	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	55	-	ns
t_f	Fall Time		-	13.5	-	ns
t_{off}	Turn-Off Time		-	-	109	ns

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Voltage	$I_{SD} = 35\text{A}$	-	0.8	1.25	V
		$I_{SD} = 15\text{A}$	-	0.8	1.0	
t_{rr}	Reverse Recovery Time	$I_{SD} = 35\text{A}, di_{SD}/dt = 100\text{A}/\mu\text{s}$	-	42	55	ns
Q_{rr}	Reverse Recovery Charge		-	48	62	nC

Notes:

- Starting $T_J = 25^\circ\text{C}$, $L = 0.26\text{mH}$, $I_{AS} = 64\text{A}$.
- Pulse width = 100s.

Typical Characteristics

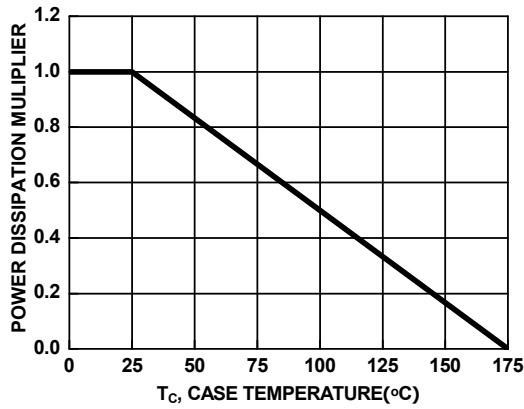


Figure 1. Normalized Power Dissipation vs Case Temperature

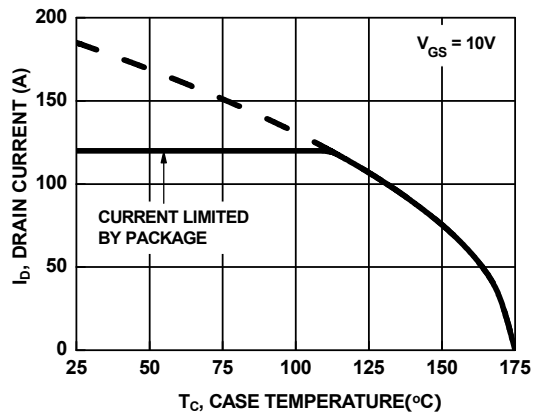


Figure 2. Maximum Continuous Drain Current vs Case Temperature

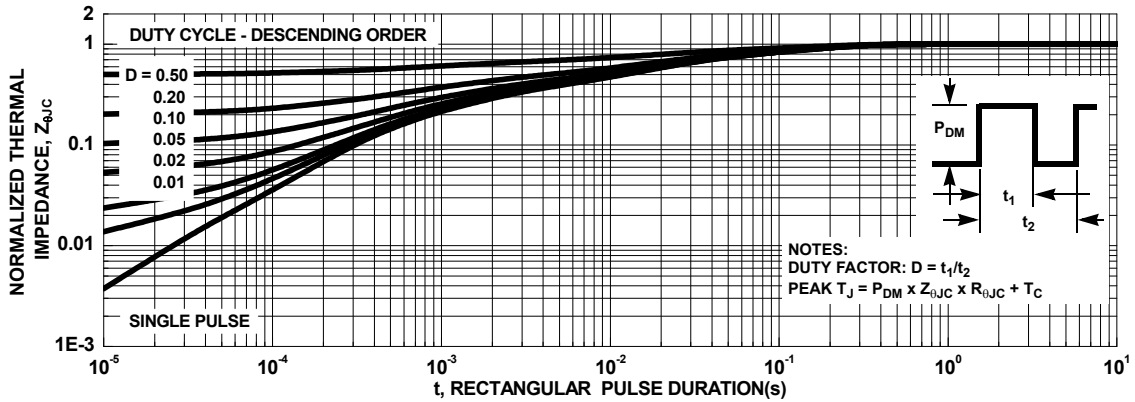


Figure 3. Normalized Maximum Transient Thermal Impedance

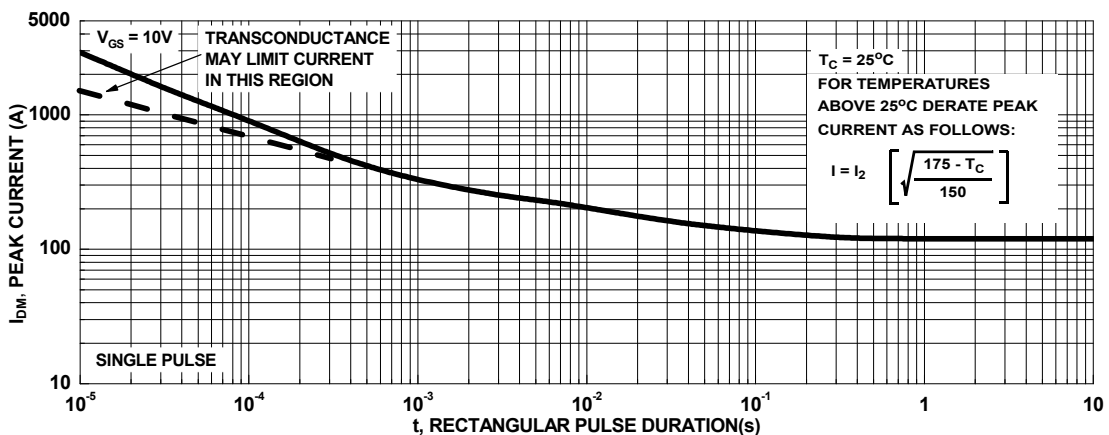


Figure 4. Peak Current Capability

Typical Characteristics

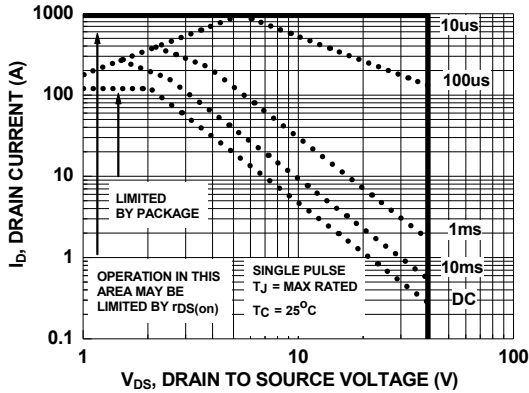
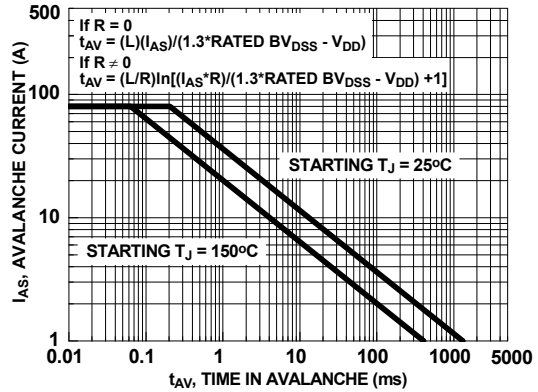


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

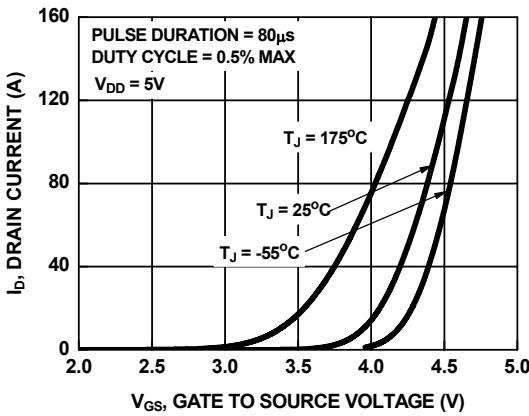


Figure 7. Transfer Characteristics

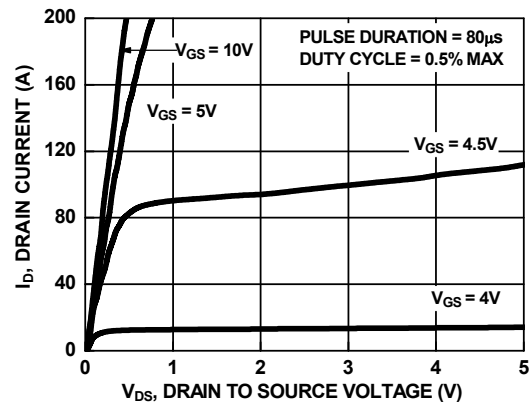


Figure 8. Saturation Characteristics

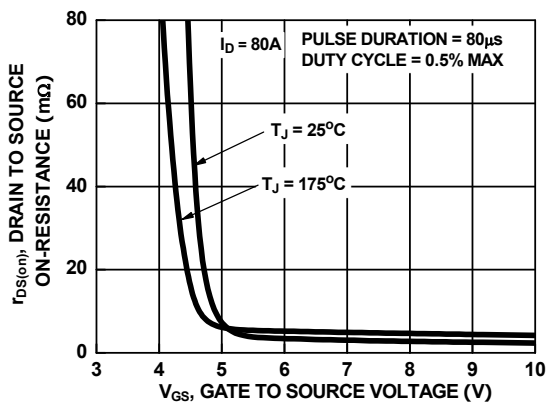


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

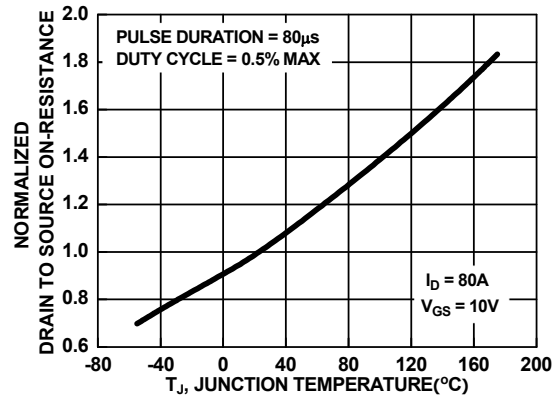


Figure 10. Normalized Drain to Source On-Resistance vs Junction Temperature

Typical Characteristics

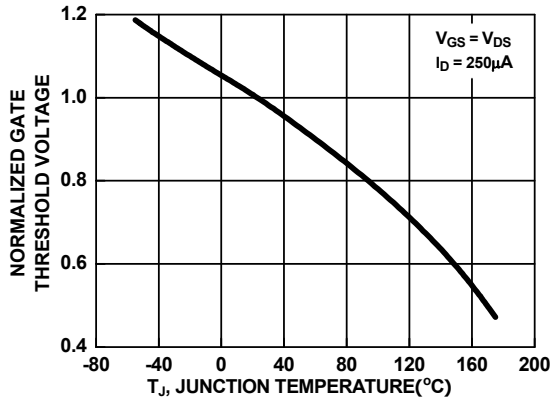


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

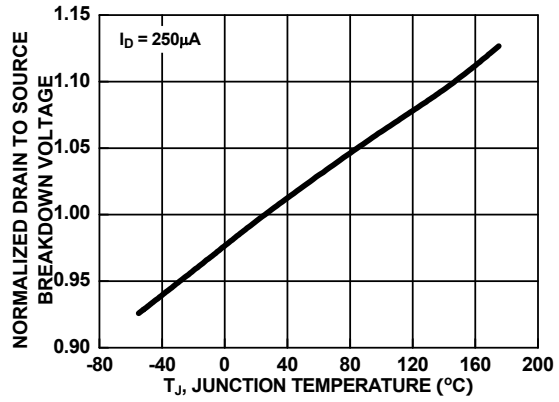


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

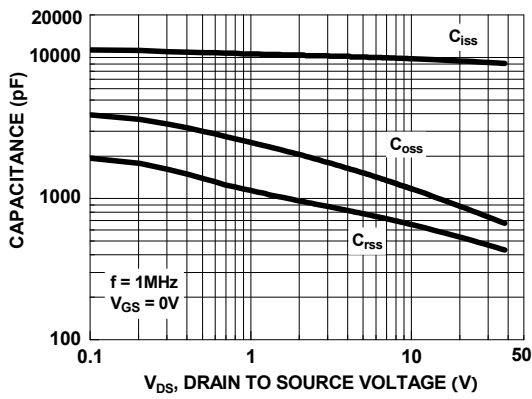


Figure 13. Capacitance vs Drain to Source Voltage

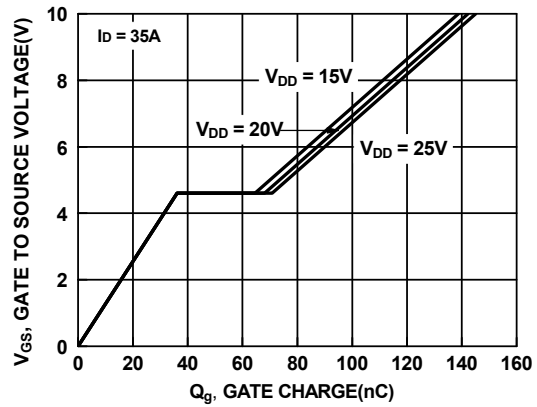



Figure 14. Gate Charge vs Gate to Source Voltage



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